IN THE CLAIMS

Please amend the claims as follows:

Claims 1 - 3 (Cancelled).

Claim 4 (Currently Amended): A polishing body, comprising:

a polishing part with a predetermined shape molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion comprising dispersed composite particles comprising an abrasive attached to a matrix material,

said abrasive being dispersed in said matrix material,

wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 5 (Previously Presented): The polishing body according to Claim 4, wherein said dispersion medium is eliminated by spray drying.

Claim 6 (Previously Presented): The polishing body according to Claim 4, wherein said aqueous dispersion further comprises a matrix material and/or an abrasive.

Claim 7 (Cancelled).

Claim 8 (Previously Presented): The polishing body according to Claim 4, wherein the polishing body is adapted for the polishing of semiconductors.

Claims 9 - 11 (Cancelled).

Claim 12 (Currently Amended): A polishing body, comprising:

a polishing part with a predetermined shape molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion comprising dispersed composite particles comprising an abrasive attached to a matrix material, said matrix material comprising a crosslinkable polymer,

said crosslinkable polymer being crosslinked during elimination of said dispersion medium, or during molding, or after molding, thereby obtaining a crosslinked structure, and

said abrasive being dispersed in said matrix material,

wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 13 (Previously Presented): The polishing body according to Claim 12, wherein said dispersion medium is eliminated by spray drying.

Claim 14 (Cancelled).

Claim 15 (Previously Presented): The polishing body according to Claim 12, wherein the polishing body is adapted for the polishing of semiconductors.

Claims 16 - 19 (Canceled).

Claim 20 (Cancelled).

Claim 21 (Previously Presented): A polishing pad, which comprises the polishing body according to Claim 4.

Claim 22 (Cancelled).

Claim 23 (Previously Presented): A polishing pad, which comprises the polishing body according to Claim 12.

Claim 24 (Cancelled).

Claim 25 (Previously Presented): A method for polishing of semiconductors, comprising:

polishing a semiconductor with the polishing body according to Claim 4.

Claim 26 (Cancelled).

Claim 27 (Previously Presented): A method for polishing of semiconductors, comprising:

polishing a semiconductor with the polishing body according to Claim 12.

Claim 28 (Previously Presented): A polishing body, comprising:

a polishing part with a predetermined shape molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion comprising dispersed composite particles comprising an abrasive attached to a matrix material

wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 29 (Previously Presented): The polishing body according to Claim 28, wherein said dispersion medium is eliminated by spray drying.

Claim 30 (Previously Presented): The polishing body according to Claim 28, wherein said aqueous dispersion further comprises a matrix material and/or an abrasive.

Claim 31 (Previously Presented): The polishing body according to Claim 28, wherein the polishing body is adapted for the polishing of semiconductors.

Claim 32 (Previously Presented): A polishing body, comprising:

a polishing part with a predetermined shape molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion containing dispersed composite particles comprising an abrasive attached to a matrix material, said matrix material comprising a crosslinkable polymer,

said crosslinkable polymer being crosslinked during elimination of said dispersion medium, or during molding, or after molding, thereby obtaining a crosslinked structure,

wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 33 (Previously Presented): The polishing body according to Claim 32, wherein said dispersion medium is eliminated by spray drying

Claim 34 (Previously Presented): The polishing body according to Claim 32, wherein the polishing body is adapted for the polishing of semiconductors.

Claim 35 (New): A polishing pad, which comprises the polishing body according to Claim 28.

Claim 36 (New): A polishing pad, which comprises the polishing body according to Claim 32.

Claim 37 (New): A method for polishing of semiconductors, comprising: polishing a semiconductor with the polishing body according to Claim 28.

Claim 38 (New): A method for polishing of semiconductors, comprising: polishing a semiconductor with the polishing body according to Claim 32.